

Serial No.: 10/800,025

Title: Titanium Copper With Excellent

Electroconductivity and Its Manufacturing Method

Filed: March 15, 2004

Atty Dkt. No.:

03520.104

Statement Regarding English Translation of Originally Filed Japanese Language Non-Provisional Patent Application

Honorable Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Sir:

The above-described non-provisional patent application was originally filed on March 14, 2004, in Japanese. The undersigned individual, having knowledge of the Japanese and English languages hereby states that the English translation of the originally filed Japanese language non-provisional patent application provided herewith is accurate.

All statements made herein of my own knowledge are true, and all statements made on information and belief are believed to be true; and further, that these statements are made with the knowledge that willful false statements, and the like so made, are punishable by fine or imprisonment, or both under Section 1001, Title 18 of the United States Code, and that such willful false statements may jeopardize the validity of the application or any patent issuing thereon.

Respectfully Submitted,

Signature:

Akira Kanoh

Typed Name:

Title:

Japanese Patent Attorney

Date:

July 13, 2005